

REMARKS

Claim 1 has been amended, and claim 7 has been cancelled. Thus, claims 1-6 and 8-20 are pending in the present application. Favorable reconsideration of the pending claims is respectfully requested.

1. Rejections Under 35 U.S.C. § 102

Claims 1-4, 6-14, 16-18 and 20 have been rejected under 35 U.S.C. §102(b) as being anticipated by U.S. Patent No. 5,780,928 to Rostoker et al. (hereafter "*Rostoker*") for the reasons set forth on pages 2-3 of the Office Action. Applicant respectfully traverses.

Claim 1 recites providing a container disposed upon the substrate, the "container in contact with the active surface of the IC chip." In contrast, *Rostoker* discloses a package body 112 and a lid 107a that surround a die 130a, but are not in contact with the active surface thereof, as shown in Figure 1b. Rather, the active surface of die 130a in *Rostoker* is only in contact with the thermally conductive fluid 114a and bond wires 150a, 150b.

Dependent claims 8 and 10 recite that "a flip chip is disposed over the active surface of the IC chip." There is no teaching or suggestion in *Rostoker* of a "flip chip" or any other kind of die or chip disposed over another chip. Rather, *Rostoker* discloses only a single die 130a, such as shown in Figure 1b.

Independent claim 12 recites a "flip chip" with an inactive surface and an active surface, with the flip chip being mounted upon a substrate, the method comprising providing a container away from the underlying substrate, as shown in Figure 1b. As disclosed in the present

application, the flip chip has an active surface that faces the underlying substrate, such as shown in Figures 7-9.

Independent claim 16 recites a "first IC chip" with an active surface, the first IC chip being mounted upon a first side of a board-on-chip (BOC) substrate, and a "second IC chip having an active surface and being disposed over the first side of the BOC substrate." In contrast, *Rostoker* discloses only a single die 130a, such as shown in Figure 1b. There is no teaching or suggestion of any second die or "chip" disposed thereover.

Claim 17 depends from claim 16 and recites "a third IC chip having an active surface and being disposed over the first side of the BOC substrate and over the second IC chip." There is no teaching or suggestion in *Rostoker* of a third chip or die disposed over other chips. Rather, as discussed previously, *Rostoker* discloses only a single die 130a as shown in Figure 1b.

Accordingly, for at least the foregoing reasons, claims 1-4, 6-14, 16-18 and 20 are not anticipated by *Rostoker*. Applicant therefore respectfully requests that the rejection of these claims under 35 U.S.C. § 102(b) be withdrawn.

2. Rejections Under 35 U.S.C. § 103

Claims 5, 15, and 19 have been rejected under 35 U.S.C. § 103(a) as being unpatentable over *Rostoker* in view of the article by Hunadi (hereinafter "*Hunadi*") for the reasons set forth on page 4 of the Office Action. Applicant respectfully traverses.

Claim 5, 15, and 19 depend respectively from claims 1, 12, and 16, and thus include the limitations thereof. There is no teaching or suggestion in *Rostoker* of the various features

disclosed in *Hunadi*. Hence, even if the teachings of *Rostoker* and *Hunadi* are combined as suggested by the Examiner, not all of the limitations of claims 5, 15, and 19 would be met.

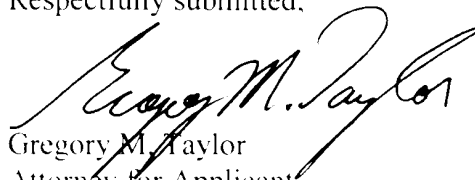
Accordingly, claims 5, 15, and 19 would not have been obvious over *Rostoker* in view of *Hunadi*. Thus, Applicant respectfully requests that the rejection of these claims under 35 U.S.C. § 103(a) be withdrawn.

CONCLUSION

In view of the foregoing, Applicant respectfully requests favorable reconsideration and allowance of the present claims. In the event there remains any impediment to allowance of the claims, which could be clarified in a telephone interview, the Examiner is respectfully requested to contact the undersigned attorney.

Dated this 19th day of September 2003.

Respectfully submitted,



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